



Please note that Cypress is an Infineon Technologies Company.

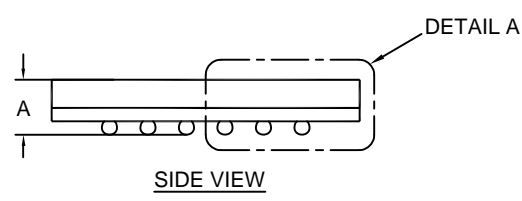
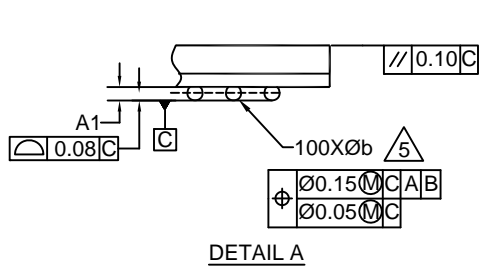
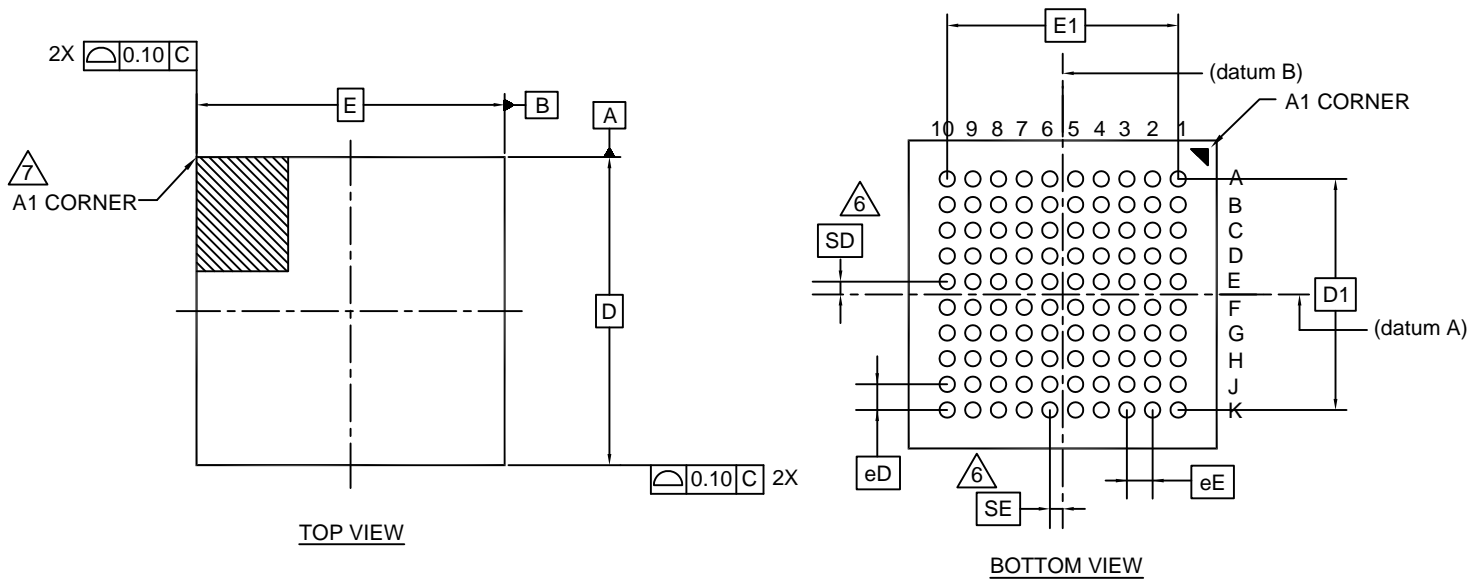
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.16	-	-
D	6.00 BSC		
E	6.00 BSC		
D1	4.50 BSC		
E1	4.50 BSC		
MD	10		
ME	10		
N	100		
Ø b	0.25	0.30	0.35
eD	0.50 BSC		
eE	0.50 BSC		
SD	0.25 BSC		
SE	0.25 BSC		

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- SOLDER BALL POSITION DESIGNATION PER JEP95, SECTION 3, SPP-020.
- "e" REPRESENTS THE SOLDER BALL GRID PITCH.
- SYMBOL "MD" IS THE BALL MATRIX SIZE IN THE "D" DIRECTION. SYMBOL "ME" IS THE BALL MATRIX SIZE IN THE "E" DIRECTION. N IS THE NUMBER OF POPULATED SOLDER BALL POSITIONS FOR MATRIX SIZE MD X ME.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
- "SD" AND "SE" ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW. WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW "SD" OR "SE" = 0. WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" = eD/2 AND "SE" = eE/2.
- A1 CORNER TO BE IDENTIFIED BY CHAMFER, LASER OR INK MARK METALIZED MARK, INDENTATION OR OTHER MEANS.
- "+" INDICATES THE THEORETICAL CENTER OF DEPOPULATED SOLDER BALLS.
- JEDEC SPECIFICATION NO. REF. : MO-195C.


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PACKAGE CODE(S) R2A100 BZ100

DRAWN BY KOTA DATE 17-NOV-15
APPROVED BY BESY DATE 17-NOV-15

CYPRESS Company Confidential
TITLE PACKAGE OUTLINE, 100 BALL VFBGA 6.0X6.0X1.0 MM R2A100/BZ100
SPEC NO. 51-85209
REV *F
SCALE : TO FIT SHEET 1 OF 2

REVISIONS			
Rev	ECN No.	Orig. of change	Reason for Revision
**	267233	HTN	NEW RELEASE
*A	301772	HTN	MOLD CAP THICKNESS UPDATE FROM 0.50 TO 0.45
*B	310955	HTN	CHANGE PART NO. FROM BV100A TO BZ100A
*C	2833453	HTN	CHANGED TEMPLATE, & TITLE FROM 100VFBGA (6X6X1.0MM) PACKAGE OUTLINE TO PACKAGE OUTLINE, 100L VFBGA 6.0X6.0X1.0 MM BZ100
*D	3159033	HTN	NO CHANGE
*E	4585887	XANC	SUNSET REVIEW, CHANGED DRAWING TEMPLATE
*F	5019186	KOTA	CHANGE DRAWING TEMPLATE, POD FORMAT AND ADD NEW PACKAGE R2A100

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TITLE PACKAGE OUTLINE, 100 BALL VFBGA 6.0X6.0X1.0 MM R2A100/BZ100	
SPEC NO. 51-85209	REV *F
SCALE : TO FIT	SHEET 2 OF 2

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